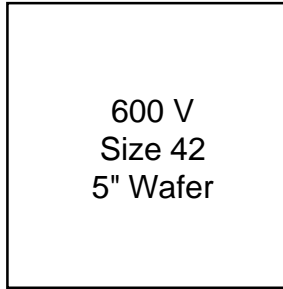


Hexfred Die in Wafer Form



Electrical Characteristics (Wafer Form)

Parameter	Description	Guaranteed (Min/Max)	Test Conditions
V_{FM}	Forward Voltage	1.4V Max.	$T_J = 25^{\circ}C, I_F = 50A$
BV_R	Reverse Breakdown Voltage	600V Min.	$T_J = 25^{\circ}C, I_R = 200\mu A$
I_{RM}	Reverse Leakage Current	20 μA Max.	$T_J = 25^{\circ}C, V_R = 600V$

Mechanical Data

Nominal Back Metal Composition, Thickness	Cr-Ni-Ag (1kA-4kA-6kA)
Nominal Front Metal Composition, Thickness	Ti-Ni-Ag (2kA-1kA-35kA)
Chip Dimensions	0.200" x 0.200"
Wafer Diameter	125mm, with std. < 100 > flat
Wafer Thickness	.015" \pm .003"
Relevant Die Mechanical Dwg. Number	01-5314
Minimum Street Width	100 Microns
Reject Ink Dot Size	0.25mm Diameter Minimum
Recommended Storage Environment	Store in original container, in dessicated nitrogen, with no contamination

Reference Standard IR packaged part (for design) : HFA100MD60C

Die Outline

